

METHOD AND SYSTEM FOR STUD BUMPING

ABSTRACT OF THE DISCLOSURE

5 According to one embodiment of the invention, a method of stud bumping includes providing a bonding head having a plurality of wire passages formed therein, disposing a plurality of wires through respective ones of the plurality of wire passages, providing a substrate having a plurality of bond pads, engaging the wires with respective ones of a first set of the bond pads, and forming a first set of stud bumps outwardly from respective ones of the first set of the bond pads.